## PATENT ASSIGNMENT

### Electronic Version v1.1
### Stylesheet Version v1.1

<table>
<thead>
<tr>
<th>SUBMISSION TYPE:</th>
<th>NEW ASSIGNMENT</th>
</tr>
</thead>
<tbody>
<tr>
<td>NATURE OF CONVEYANCE:</td>
<td>ASSIGNMENT</td>
</tr>
</tbody>
</table>

### CONVEYING PARTY DATA

<table>
<thead>
<tr>
<th>Name</th>
<th>Execution Date</th>
</tr>
</thead>
<tbody>
<tr>
<td>Woo-Seok JEON</td>
<td>11/11/2009</td>
</tr>
<tr>
<td>Jung-In PARK</td>
<td>11/11/2009</td>
</tr>
<tr>
<td>Hi-Kuk LEE</td>
<td>11/11/2009</td>
</tr>
<tr>
<td>Byung-Uk KIM</td>
<td>11/11/2009</td>
</tr>
<tr>
<td>Dong-Min KIM</td>
<td>11/11/2009</td>
</tr>
<tr>
<td>Ja-Hun BYEON</td>
<td>11/11/2009</td>
</tr>
</tbody>
</table>

### RECEIVING PARTY DATA

<table>
<thead>
<tr>
<th>Name</th>
<th>Samsung Electronics Co., Ltd.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Street Address</td>
<td>416, Maetan-Dong, Yeongtong-gu, Gyeonggi-do</td>
</tr>
<tr>
<td>City</td>
<td>Suwon-si</td>
</tr>
<tr>
<td>State/Country</td>
<td>KOREA, REPUBLIC OF</td>
</tr>
<tr>
<td>Postal Code</td>
<td>443-803</td>
</tr>
</tbody>
</table>

### PROPERTY NUMBERS Total: 1

<table>
<thead>
<tr>
<th>Property Type</th>
<th>Number</th>
</tr>
</thead>
<tbody>
<tr>
<td>Application Number</td>
<td>12620988</td>
</tr>
</tbody>
</table>

### CORRESPONDENCE DATA

<table>
<thead>
<tr>
<th>Fax Number</th>
<th>(703)288-5139</th>
</tr>
</thead>
</table>

*Correspondence will be sent via US Mail when the fax attempt is unsuccessful.*

<table>
<thead>
<tr>
<th>Phone</th>
<th>703-288-5105</th>
</tr>
</thead>
</table>

<table>
<thead>
<tr>
<th>Email</th>
<th><a href="mailto:patent@park-law.com">patent@park-law.com</a></th>
</tr>
</thead>
</table>

<table>
<thead>
<tr>
<th>Correspondent Name</th>
<th>H.C. Park &amp; Associates, PLC</th>
</tr>
</thead>
</table>

<table>
<thead>
<tr>
<th>Address Line 1:</th>
<th>8500 Leesburg Pike</th>
</tr>
</thead>
</table>

<table>
<thead>
<tr>
<th>Address Line 2:</th>
<th>Suite 7500</th>
</tr>
</thead>
</table>

<p>| Address Line 4:   | Vienna, VIRGINIA 22182      |</p>
<table>
<thead>
<tr>
<th>ATTORNEY DOCKET NUMBER:</th>
<th>P2807US00</th>
</tr>
</thead>
<tbody>
<tr>
<td>NAME OF SUBMITTER:</td>
<td>Hae-Chan Park</td>
</tr>
</tbody>
</table>

Total Attachments: 6
source=P2807US00_Assignment#page1.tif
source=P2807US00_Assignment#page2.tif
source=P2807US00_Assignment#page3.tif
source=P2807US00_Assignment#page4.tif
source=P2807US00_Assignment#page5.tif
source=P2807US00_Assignment#page6.tif
ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

☑ an application for United States Letters Patent entitled PHOTORESIST COMPOSITION AND METHOD OF FABRICATING THIN FILM TRANSISTOR SUBSTRATE ("Application");

☐ upon which United States Letters Patent, Patent Number _____________ , has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

Samsung Electronics Co., Ltd.
416 Maelan-dong, Yeongtong-gu
Gyeonggi-do
Suwon-si
Republic of Korea

Samsung Electronics Co., Ltd. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary
or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.
First Inventor's Name: Sang-Hyun YUN
Address: #972-11, Ingye-dong, Paldal-gu
               Suwon-si
               Gyeonggi-do
               Republic of Korea
First Inventor's Signature: Sang Hun Yun
Date: November 11, 2009

Second Inventor's Name: Woo-Seok JEON
Address: #403-1001, Shindong-a Apt., Sadang 2-dong
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               Seoul
               Republic of Korea
Second Inventor's Signature: Woo-Seok Jeon
Date: November 11, 2009

Third Inventor's Name: Jung-In PARK
Address: F306, 52-12, Gokbanjeong-dong, Gwoneun-gu
               Suwon-si
               Gyeonggi-do
               Republic of Korea
Third Inventors' Signature: Jung In. Park.
Date: November 11, 2009

Fourth Inventor's Name: Hi-Kuk LEE
Address: #747-1, DaeDae-ri, Yangji-rmeon
               Yongin-si
               Gyeonggi-do
               Republic of Korea
Fourth Inventor’s Signature: J. Jang

Date: November 11, 2009

Fifth Inventor’s Name: Byung-Uk Kim
Address: 625-3, Yodang-ri, Yanggam-myeon
          Hwaseong-si,
          Gyeonggi-do,
          Republic of Korea

Fifth Inventor’s Signature: 

Date: 

Sixth Inventor’s Name: Dong-Min Kim
Address: 625-3, Yodang-ri, Yanggam-myeon
          Hwaseong-si
          Gyeonggi-do
          Republic of Korea

Sixth Inventor’s Signature: 

Date: 

Seventh Inventor’s Name: Seung-Ki Kim
Address: 625-3, Yodang-ri, Yanggam-myeon
          Hwaseong-si
          Gyeonggi-do
          Republic of Korea

Seventh Inventor’s Signature: 

Date: 
Fourth Inventor's Signature: ____________________________
Date: ________________________________

Fifth Inventor's Name: Byung-Uk KIM
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Fifth Inventor's Signature: ____________________________
Date: November 11, 2009

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Sixth Inventor's Signature: ____________________________
Date: November 11, 2009

Seventh Inventor's Name: Seung-Ki KIM
Address: 625-3, Yodang-ri, Yanggam-myeon
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Gyeonggi-do
Republic of Korea

Seventh Inventor's Signature: ____________________________
Date: November 11, 2009
Eighth Inventor's Name: Ja-Hun BYEON
Address: 625-3, Yodang-ri, Yanggam-myeon
Hwaseong-si
Gyeonggi-do
Republic of Korea

Eighth Inventor's Signature: ____________________________
Ja-Hun BYEON

Date: ____________________________
November 11, 2009